Low Cost, High Efficiency Push-Pull Boost Converter

Low Cost Regulated LDO

Low THD, Sine wave Oscillator
*Can be generated using MCU based SPWM

Class A Amplifier
*Can be Half Bridge for SPWM signals

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Power Supply Design for Flame Rod Excitation

PCB Number: TIDA-01428
PCB Rev: E1

<table>
<thead>
<tr>
<th>Variant</th>
<th>Label Text</th>
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<tbody>
<tr>
<td>001</td>
<td>E1</td>
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Variant/Label Table

- **Variant**: Different labels for different variants
- **Label Text**: Text to be placed on the PCB

- **PCB Label**
  - Size: 0.65" x 0.20"

Assembly Notes:
- **ZZ1**: Important Assembly Note
- **ZZ2**: These assemblies are ESD sensitive, ESD precautions shall be observed.
- **ZZ3**: These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- **ZZ4**: These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Text on the PCB:
- **PCB Label**: PCB information
- **PCB Logo**: Logo information
- **Pb-Free Symbol**: Pb-free symbol information
- **FCC Disclaimer**: FCC disclaimer information

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